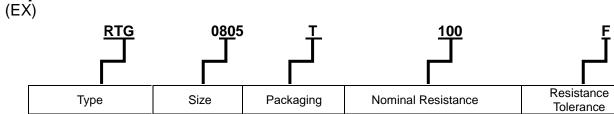


Document No.	IE-SP-103
Released Date	2019/10/16
Page No.	1

1 Scope:

- 1.1 This specification is applicable to lead free and halogen free of RoHS directive for RTG series Pulse-Proof thick film chip resistors.
- 1.2 The product is for general electronic purpose.

2 Explanation Of Part Numbers:



			I		
Туре	Size	Packaging	Nominal Resi	stance	Resistance Tolerance
Pulse-Proof Thick Film Chip Resistors	0402 0603 0805 1206 2010 2512	T : Taping	3	ries .2Ω=10R2 KΩ=1002	D=± 0.5% F=± 1%

3 General Specifications:

5011014	Rate	May May		TCD	Resistan	ce Range
Туре	Power at 70℃	Working Voltage	Overload Voltage	T.C.R. (ppm/℃)	D(±0.5%) E-96	F(±1%) E-96
RTG0402	<u>1</u> W	50V	100V	±200	1Ω≦R≦10M	
RTG0603	$\frac{1}{3}$ W	75V	150V	±200	1Ω≦R≦10M	
RTG0805	1 3.	150V	300V	±200	1Ω≦R≦150KΩ	
RTG1206	<u>1</u> W	200V	400V	±200	1Ω≦R≦150KΩ	
RTG2010	3 4 W	200V	400V	±200	1Ω≦R≦150KΩ	
RTG2512	1W	200V	400V	±200	1Ω≦R≦	≦150KΩ
Operating Temperature Range			ange		-55℃ ~+155℃	

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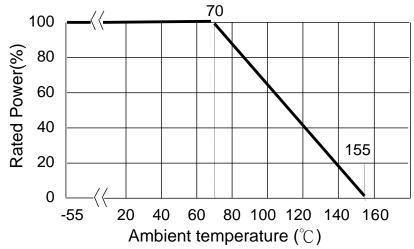


Document No.	IE-SP-103
Released Date	2019/10/16
Page No.	2

3.1 Power Derating Curve:

Operating Temperature Range : - 55 \sim 155 $^{\circ}$ C

For resistors operated in ambient temperatures above 70°C , power rating shall be derated in accordance with figure below $^{\circ}$



3.2 Voltage Rating or Current Rating

Rated Voltage: The resistor shall have a DC continuous working voltage or a rms. AC continuous working voltage at commercial-line frequency and wave form corresponding to the power rating, as determined from the following:

$$E = \sqrt{R \times P}$$

E= Rated voltage (v)

P= Power rating (w)

R= Nominal resistance(Ω)

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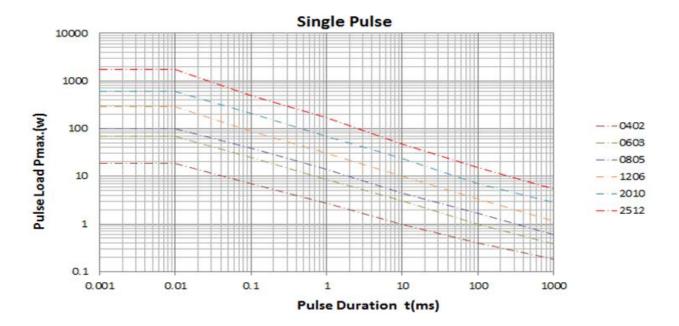
Document No.	IE-SP-103
Released Date	2019/10/16
Page No.	3

3.3 Pulse Loading Capability

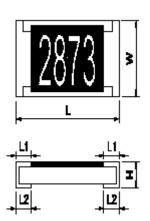
Single Pulse Load:

Pulse on a regular basis; maximum permissible peak pulse power (Pmax) as a function of a pulse duration.

 $V_{\text{peak}} \! \leq \! 0402 (100 \text{V}) \, \cdot \, 0603 (150 \text{V}) \, \cdot \, \, 0805 (300 \text{V}) \, \cdot \, \, 1206 (400 \text{V}) \, \cdot \, \, 2010 (400 \text{V}) \, \cdot \, \, 2512 (400 \text{V})$



4 Dimensions:



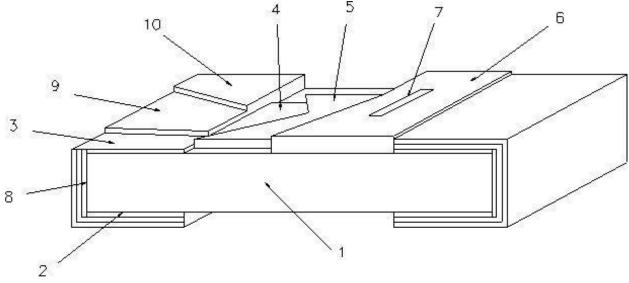
						Unit:mm
Туре	Dimension Size Code	L	W	Н	L1	L2
RTG	0402	1.00±0.10	0.50±0.05	0.30±0.05	0.20±0.10	0.25±0.10
RTG	0603	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.15	0.30±0.15
RTG	0805	2.00±0.10	1.25±0.10	0.50±0.10	0.35±0.20	0.35±0.15
RTG	1206	3.05±0.10	1.55±0.10	0.50+0.10 -0.05	0.45±0.20	0.35±0.15
RTG	2010	5.00±0.20	2.50±0.20	0.55±0.10	0.60±0.20	0.60±0.20
RTG	2512	6.30±0.20	3.20±0.20	0.55±0.10	0.60±0.20	0.60±0.20

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Document No. IE-SP-103
Released Date 2019/10/16
Page No. 4

5 Structure Graph:



1	Ceramic substrate	6	2nd Protective coating
2	Bottom inner electrode	7	Marking
3	Top inner electrode	8	Terminal inner electrode
4	Resistive layer	9 Ni plating	
5	1st Protective coating	10	Sn plating

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Document No.	IE-SP-103
Released Date	2019/10/16
Page No.	5

6 Reliability Test:

6.1 Electrical Performance Test

Item	Conditions	Specifications
Item	Conditions	Resistors
Temperature Coefficient of Resistance	TCR (ppm/°C) = $\frac{(R2-R1)}{R1 (T2-T1)} \times 10^6$ R1: Resistance at room temperature R2: Resistance at -55°C or +125°C T1: Room temperature T2: Temperature -55°C or +125°C	Refer to item 3. general specifications
Short Time Overload	Refer to JIS-C5201-1 4.8 Applied 2.5 times rated voltage for 5 seconds and release the load for about 30 minutes, then measure its resistance variance rate. (Rated voltage refer to item 3. general specifications) Refer to JIS-C5201-1 4.13	ΔR%=±0.5%
Insulation Resistance	Put the resistor in the fixture, add 100 VDC in + ,- terminal for 60 sec then measured the insulation resistance between electrodes and insulating enclosure or between electrodes and base material. Refer to JIS-C5201-1	$\geq 10^{9}\Omega$
Dielectric	Put the resistor in the fixture, add VAC (see spec. below) in +,- terminal for. RTG0402 \ 0603apply 300 VAC 1 minute. RTG0805 \ 1206 \ 2010 \ 2512apply 500 VAC 1 minute. Refer to JIS-C5201-1 4.7	No short or burned on the appearance.
Intermittent Overload	Put the tested resistor in chamber under temperature 25±2°C and load the rated DC voltage for 1 sec on , 25 sec off , 10000^{+400}_{0} test cycles, then it be left at no-load for 1 hour , then measure its resistance variance rate. Refer to JIS-C5201-1 4.13	∆R%=±1.0%
ESD	Put the specimens on the test fixture and apply ±3KVDC on terminals for 1sec .Afterwards, the specimens stabilize for30min or more and measure of its resistance variance rate. Refer to EIAJED-4701-300 304	∆R%=±5.0%

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Document No. IE-SP-103
Released Date 2019/10/16
Page No. 6

6.2 Mechanical Performance Test

Test:The resistor mounted on the board applied 5hpushingforce on the sample rear for 10 sec. Test:The resistor mounted on the board along to the sample rear for 10 sec. Test:The resistor mounted on the board slowly add force on the sample rear until the sample termination is breakdown. Refer to JIS-C5201-1 4.16 The tested resistor be immersed into isopropyl alcohol of 20-25°C for 5 minutes, and then the resistor is left in the room for 48 hrs., and measured its resistance to Solvent variance rate. Refer to JIS-C5201-1 4.29 Preconditioning: Put the tested resistor in the apparatus of PCT, at a temperature of 105°C, humidity of 100% RH, and pressure of 1.22×10° Pa for a duration of 4 hours. Then after left the tested resistor in room temperature 205±5°C for 2±0.5 sec, then the resistor is left as placed under microscope to observe its solder area. Refer to JIS-C5201-1 4.17 Test method 1 (solder pot test): The tested resistor be immersed into molten solder of 260+5/0°C for 30+1/-0. Test method 2 (solder pot test): The tested resistor be immersed into molten solder of 260+5/0°C for 30+1/-0. Test method 2 (solder pot test): The tested resistor be immersed into molten solder of 260+5/0°C for 30+1/-0. Test method 3 (Electric iron test): Preheating the electric iron on electrode termination, as after that step placed the iron over 60 min. and measured its resistance variance rate. Refer to JIS-C5201-1 4.18 Bending Strength: Joint Strength	6.2 IVIE	chanical Performance Test	
Test1: The resistor mounted on the board applied 5Npushingforce on the sample rear for 10 sec. Test2: The resistor mounted on the board slowly add force on the sample rear until the sample termination is breakdown. Refer to JIS-C5201-1 4.16 The tested resistor be immersed into isopropyl alcohol of 20-25 C for 5 minutes. Resistance to Solvent Refer to JIS-C5201-1 4.29 Preconditioning: Put the tested resistor in the apparatus of PCT, at a temperature of 105°C, hundridy of 100% RPI, and pressure of 1.22x10° Pa for a duration of 4 hours. Then after left the tested resistor in room temperature for 2 hours or more. Solderability The resistor be immersed into solder pot in temperature 235±5°C for 2±0.5 sec, then the resistor is left as placed under microscope to observe its solder area. Refer to JIS-C5201-1 4.17 Test method. The tested resistor be immersed into molten solder of 260+5/-0°C for 10 +1/-0 seconds. Then the resistor is left in the room for 1 hour. The tested resistor be immersed into molten solder of 260+5/-0°C for 30+1/-0 seconds. Then the resistor is left as placed under microscope to observe its solder area. Refer to JIS-C5201-1 4.17 Test method 2 (solder pot test): The tested resistor be immersed into molten solder of 260+5/-0°C for 30+1/-0 seconds. Then the resistor is left as placed under microscope to observe its solder area. Test item 1: (1)Variance rate on resistance area. Test item 2: (2)Test method 3 (Electric iron test): Preheating the electroid on the resistor of the preheating the placed the iron over 60 min. and measured its resistance variance rate. D.RTG02 103 -055-5mm RTG2106-3mm RTG2106-3mm RTG2206-3mm RTG2206-3c5-5mm RTG2106-3c5-5mm RTG2107-3c5-5mm RTG2107-3c5-5mm RTG2107-3c5-5mm RTG2107-3c5-5mm RTG2107-3c5-5mm RTG2107-3c5-5mm RTG2107-3c	Item	Conditions	Specifications Resistors
Resistance to Solderability Resistance to Solvent The tested resistor is left in the room for 48 hrs., and measured its resistance variance rate. Refer to JIS-C5201-1 4.29 Preconditioning Put the tested resistor in the apparatus of PCT, at a temperature of 105 °C, humidity of 100% RH, and pressure of 1.22×10° Pa for a duration of 4 hours. Then after left the tested resistor in room temperature 235±5 °C for 2±0.5 sec, then the resistor is left as placed under microscope to observe its solder area. Refer to JIS-C5201-1 4.17 ⑤ Test method 1 (solder pot test): The tested resistor be immersed into molten solder of 260+5/-0 °C for 10+1/-0 seconds. Then the resistor is left in the room for 1 hour. ⑥ Test method 2 (solder pot test): The tested resistor be immersed into molten solder of 260+5/-0 °C for 30+1/-0 seconds. Then the resistor is left as placed under microscope to observe its solder area. Resistance to Soldering Heat Preheating temperature: 350±10 °C test method 3 (Electric iron test): Preheating temperature: 350±10 °C test method 3 (Electric iron test): Preheating temperature: 350±10 °C test method 3 (Electric iron test): Preheating temperature: 350±10 °C test method 3 (Electric iron test): Preheating the electric iron on on electrode termination, as after that step placed the iron over 60 min. and measured its resistance variance rate. Refer to JIS-C3201-1 4.18 ⑤ Bending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D.RTG02 · 03 · 05=5mm RTG12010 · 2512=2mm Resistor Resistor is left in the resistor of testing treductive board Prevenute Prevenute Variance rate on resistance AR%=±1.0% AR%=±1.0% AR%=±1.0%		rear for 10 sec. Test2:The resistor mounted on the board slowly add force on the sample rear until the sample termination is breakdown.	Test1:No evidence of mechanical damage.
Preconditioning: Put the tested resistor in the apparatus of PCT, at a temperature of 105°C, humidity of 100% RH, and pressure of 1.22×10° Pa for a duration of 4 hours. Then after left the tested resistor in room temperature for 2 hours or more. Test method: The resistor be immersed into solder pot in temperature 235±5°C for 2±0.5 section then the resistor is left as placed under microscope to observe its solder area. Refer to JIS-C5201-1 4.17 ③Test method 1 (solder pot test): The tested resistor be immersed into molten solder of260+5/-0°C for 10 +1/-0seconds. Then the resistor is left in the room for 1 hour. The tested resistor be immersed into molten solder of260+5/-0°C for 30+1/-0seconds. Then the resistor is left as placed under microscope to observe its solder area. Beasistance to Soldering Heat When the state of th		The tested resistor be immersed into isopropyl alcohol of 20~25℃ for 5 minutes, then the resistor is left in the room for 48 hrs., and measured its resistance variance rate.	ΔR%=±0.5%
Test method 1 (solder pot test): The tested resistor be immersed into molten solder of 260+5/-0°C for 10 +1/-0seconds. Then the resistor is left in the room for 1 hour. □ Test method 2 (solder pot test): The tested resistor be immersed into molten solder of 260+5/-0°C for 30+1/-0 seconds. Then the resistor is left as placed under microscope to observe its solder area. □ Test method 3 (Electric iron test): Preheating temperature: 350±10°C Electric iron preheating time: 3+1/-0 sec Preheating the electric iron on electrode termination, as after that step placed the iron over 60 min. and measured its resistance variance rate. Refer to JIS-C5201-1 4.18 □ Bending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTG02 \ 0.3 \ 0.5=5mm RTG1206=3mm RTG2010 \ 2512=2mm Resistator Testing circuit board AR%=±1.0% Canount of band) Canount of band)	Solderability	Preconditioning: Put the tested resistor in the apparatus of PCT, at a temperature of 105°C, humidity of 100% RH, and pressure of 1.22×10⁵ Pa for a duration of 4 hours. Then after left the tested resistor in room temperature for 2 hours or more. Test method: The resistor be immersed into solder pot in temperature 235±5°C for 2±0.5 sec, then the resistor is left as placed under microscope to observe its solder area.	Solder coverage over 95%
Sending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTG02 \ 03 \ 05=5mm RTG1206=3mm RTG2010 \ 2512=2mm Testing circuit board Supporting jig Chilp resistor (Arrount of band)	Resistance to Soldering Heat	 Test method 1 (solder pot test): The tested resistor be immersed into molten solder of260+5/-0°C for 10 +1/-0seconds. Then the resistor is left in the room for 1 hour. Test method 2 (solder pot test): The tested resistor be immersed into molten solder of260+5/-0°C for 30+1/-0 seconds. Then the resistor is left as placed under microscope to observe its solder area. Test method 3 (Electric iron test): Preheating temperature: 350±10°C Electric iron preheating time: 3+1/-0 sec Preheating the electric iron on electrode termination, as after that step placed the iron over 60 min. and measured its resistance variance rate. 	 (1)Variance rate on resistance ΔR%=±0.5% Test item 2: (1)Solder coverage over 95%. (2)The underlying material (such as ceramic) shall not be visible at thecrest corner area of the electrode. Test item 3: (1)Variance rate on resistance
	Strength	©Bending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTG02 \ 03 \ 05=5mm RTG1206=3mm RTG2010 \ 2512=2mm Resistor Testing circuit board Chip resistor (Amount of bend)	
		Refer to JIS-C5201-1 4.33	

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Released Date 2019/10/16
Page No. 7

6.3 Environmental Test

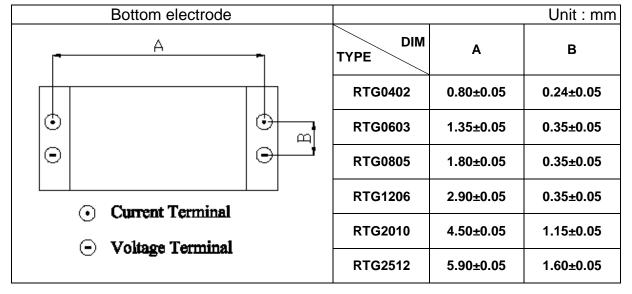
Item		Conditions			Specifications
пеш		Conditions		Resistors	
Resistance to Dry Heat	hours.The and meas	Put tested resistor in chamber under temperature 155±5℃ for 1000 +48/-0 nours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25			
Put the tested resistor in the chamber under the Thermal Shock which shown in the following table shall be repeated 300 times consecutively. Then leaving the tested resistor in the room temperature for 1 hours, and measure its resistance variance rate.					
Thermal Shock		Testing Condi			
THEITIAI SHOCK		Lowest Temperature	-55±5°C		
		Highest Temperature	125±5°ℂ		
		Temperature-retaining time	15 minutes each		
	Refer to M	IIL-STD 202 Method 107			
Loading Life in Moisture	Put the tested resistor in the chamber under temperature 40±2°C, relative ΔR%=±1.0% humidity 90~95% and load the rated voltage for 90 minutes on, 30 minutes off, total 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.24				
Load Life	Put the tested resistor in chamber under temperature 70±2°C and load the rated voltage for 90 minutes on, 30 minutes off, total 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25				

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Released Date	2019/10/16
Page No.	8

7 Measurement Point:



8 Plating Thickness:

8.1 Ni: \geq 2 μ m

8.2 Sn(Tin):≥3µm

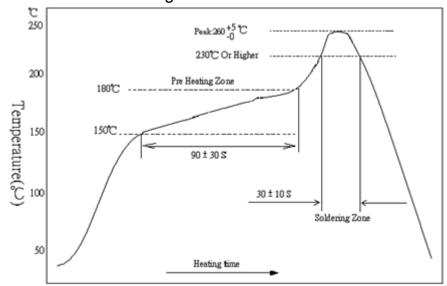
8.3 Sn(Tin):Matte Sn

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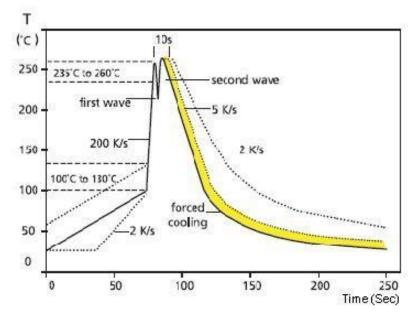
Document No.	IE-SP-103
Released Date	2019/10/16
Page No.	9

- 9 Technical application notes: (This is for recommendation, please customer perform adjustment according to actual application)
 - 9.1 Recommend Soldering Method:
 - 9.1.1 Lead Free IR Reflow Soldering Profile



Remark: The peak temperature of soldering heat is 260 +5/-0 °C for 10 seconds

9.1.2 Lead Free Double-Wave Soldering Profile.(This applies to 0603 size inclusive above products)



9.1.3 Soldering Iron: temperature 350°C±10°C , dwell time shall be less than 3 sec.

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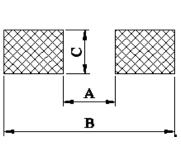


Document No.	IE-SP-103
Released Date	2019/10/16
Page No.	10

Unit:mm

9.2 Recommend Land Pattern Design (For Reflow Soldering):

When a component is soldered, the resistance after soldering changes slightly depending on the size of the soldering area and the amount of soldering. When designing a circuit, it is necessary to consider the effect of a decrease or increase in its resistance.



		`	J
DIM TYPE	А	В	O
RTG0402	0.5	1.5	0.6
RTG0603	0.8	2.1	0.9
RTG0805	1.2	3.0	1.3
RTG1206	2.2	4.2	1.6
RTG2010	3.5	6.1	2.8
RTG2512	3.8	8.0	3.5

9.3 Environment Precautions:

This specification product is for general electronic use, ABCO will not be responsible for any damage, cost or loss caused by using this specification product in any special environment. If other applications need to confirm with ABCO.

If consumer intends to use our Company product in special environment or condition (including but not limited to those mentioned below), then will need to make individual recognition of product features and reliability accordingly.

- (a) Used in high temperature and humidity environment
- (b) Exposed to sea breeze or other corrosive gas, such as Cl2 \ H2S \ NH3 \ SO2 and NO2.
- (c) Used in non-verified liquids including water, oil, chemical and organic solvents.
- (d) Using non-verified resin or other coating material to seal or coat our Company product.
- (e) After soldering, it is necessary to use water-soluble detergents to clean residual solder fluxes, even though no-clean fluxes are recommended.

9.4 Momentary Overload Precautions:

The product might be out of function when momentary overloaded. Please make sure to avoid momentary overloading while using and preserving.

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Document No.	IE-SP-103		
Released Date	2019/10/16		
Page No.	11		

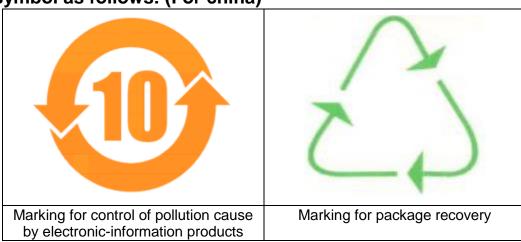
9.5 Operation and Processing Precautions:

- (a) Avoid damage to the edge of resistor and protective layer caused by mechanical stress.
- (b) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
- (c) Make sure the power rating is under the limit when using the resistor. When power rating is over the limit, the resister will be overloaded. There might be machinery damage due to the climbing temperature.
- (d) If the resister will be exposed under massive impact load (shock wave) in a short period of time, the working environment must be set up well before use.
- (e) Please make evaluation and confirmation when the product is well used in your company and have a through consideration of it's fail-safe design to ensure the system safety.

10 Storage and transportation requierment:

- 10.1 The temperature condition must be controlled at 25±5°C, the R.H. must be controlled at 60±15%. The stock can maintain quality level in two years.
- 10.2 Please avoid the mentioned harsh environment below when storing to ensure product performance and its' weldability. Places exposed to sea breeze or other corrosive gas, such as Cl₂ \ H₂S \ NH₃ \ SO₂ and NO₂.
- 10.3 When the product is moved and stored, please ensure the correct orientation of the box. Do not drop or squeeze the box. Otherwise, the electrode or the body of the product may be damaged.

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Released Date	2019/10/16	
Page No.	12	

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